

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 3, line 14 that continues onto page 4 with the following rewritten paragraph:

-- ~~In a patent document 1 Japanese Patent Laid-Open Publication No. 62950/1993 ("JP '950")~~, there is disclosed a method for sticking a protective tape to a semiconductor wafer, wherein a protective tape capable of controlling adhesive strength by proper treatment is used and the protective tape is stuck only to the peripheral region of a semiconductor wafer with a strong adhesive strength. To be brief, in this method, an ultraviolet ray-curable type adhesive tape is used as the protective film, and prior to sticking of the tape to the semiconductor wafer, the adhesive layer which is to be brought into contact with the circuit-formed region of the wafer is cured, and fixing of the wafer is carried out only in the peripheral region of the wafer. --

Please replace the paragraph at page 4, line 3 with the following rewritten paragraph:

-- In the method of the ~~patent document 1~~ aforementioned JP '950, however, the cured adhesive layer and the uncured adhesive layer are present on the same plane. Therefore, if the height of the bump is increased, the adhesive layer cannot be stuck to the edge of the wafer because of an obstacle of the bump. On this account, such a defect that the cleaning water penetrates to the circuit surface side as shown in Fig. 4 has not been improved sufficiently. --

Please DELETE the paragraph at page 4, line 11.

Please DELETE the section headings at page 4, lines 14 and 15.

Please replace the section heading at page 5, line 4 with the following rewritten section heading.

-- **MEANS TO SOLVE THE PROBLEM SUMMARY OF THE INVENTION**

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Please DELETE the section heading at page 7, line 14.

Please replace the paragraphs beginning at page 8, line 3 and ending on line 21 with the following rewritten paragraphs:

-- Fig. 1 is a sectional view of a surface protective sheet of the present invention; ;

Fig. 2 is a perspective view of a surface protective sheet of the present invention; ;

Fig. 3 shows back surface grinding of a wafer wherein a surface protective sheet of the present invention has been stuck to a bump-formed surface of the wafer; ; and

Fig. 4 shows back surface grinding of a wafer wherein a conventional surface protective adhesive sheet "A" has been stuck to a bump-formed surface of the wafer.

Description of symbols

1: base sheet

2: adhesive layer

3: opening portion

4: semiconductor wafer

5: bump

10: surface protective sheet

A: conventional surface protective adhesive sheet--

Please replace the section heading at page 8, line 23 with the following rewritten section heading.

-- ~~BEST MODE FOR CARRYING OUT~~DETAILED DESCRIPTION OF
THE INVENTION --

Please DELETE the section heading page 22, line 22.

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